



## P-Channel Power MOSFE

SI2305DS



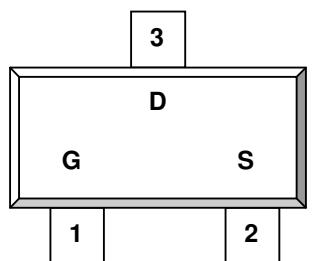
## DESCRIPTION

SI2305DS is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density, DMOS trench technology. This high-density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management, other battery powered circuits, and low in-line power loss are required. The product is in a very small outline surface mount package.

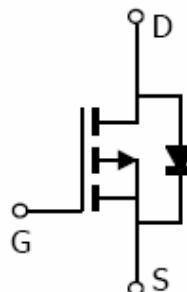
## FEATURE

- 20V/3.3A,  $R_{DS(ON)} = 68m\Omega$  @ $V_{GS} = 4.5V$
- 20V/2.2A,  $R_{DS(ON)} = 89m\Omega$  @ $V_{GS} = 2.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

## PIN CONFIGURATION SOT-23



1.Gate 2.Source 3.Drain



Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	
Continuous Drain Current	$I_D$	-3.3	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	-10	
Maximum Power Dissipation <sup>2)</sup>	$P_D$	1.25	W
		0.8	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) <sup>2)</sup>	$R_{thJA}$	100	°C/W
Junction-to-Ambient Thermal Resistance (PCB mounted) <sup>3)</sup>		166	

## Notes

- 1) Pulse width limited by maximum junction temperature.
- 2) Surface Mounted on FR4 Board,  $t \leq 5$  sec.
- 3) Surface Mounted on FR4 Board.



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## ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Drain-Source On-State Resistance <sup>1)</sup>	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -3.3A$		64	110	$m\Omega$
		$V_{GS} = -2.5V, I_D = -2.2A$		89	140	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	0.4		1	V
Zero Gate Voltage Drain Current 0	$I_{DSS}$	$V_{DS} = -20V, V_{GS} = 0V$			-1	$\mu A$
		$V_{DS} = -16V, V_{GS} = 0V, TJ = 55^\circ C$			-10	
Gate Body Leakage	$I_{GSS}$	$V_{GS} = \pm 10V, V_{DS} = 0V$			$\pm 100$	nA
Forward Transconductance <sup>1)</sup>	$g_{fs}$	$V_{DS} = -5V, I_D = -2.8A$		6.5	—	S
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS} = -6V, I_D \approx -2.3A$		5.8	10	nC
Gate-Source Charge	$Q_{gs}$			0.85		
Gate-Drain Charge	$Q_{gd}$			1.7		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -6V, RL = 6\Omega$ $I_D \approx -1A, V_{GEN} = -4.5V$ $R_G = 6\Omega$		13	25	ns
Turn-On Rise Time	$t_r$			36	60	
Turn-Off Delay Time	$t_{d(off)}$			42	70	
Turn-Off Fall Time	$t_f$			34	60	
Input Capacitance	$C_{iss}$	$V_{DS} = -6V, V_{GS} = 0V$ $f = 1.0 \text{ MHz}$		415		pF
Output Capacitance	$C_{oss}$			223		
Reverse Transfer Capacitance	$C_{rss}$			87		
<b>Source-Drain Diode</b>						
Max. Diode Forward Current	$I_S$				-1.6	A
Diode Forward Voltage	$V_{SD}$	$I_S = -1.0A, V_{GS} = 0V$		-0.8	-1.2	V

<sup>1)</sup> Pulse test: pulse width <= 300us, duty cycle <= 2%



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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

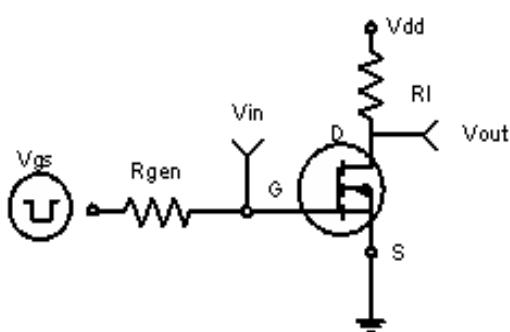


Figure 1:Switching Test Circuit

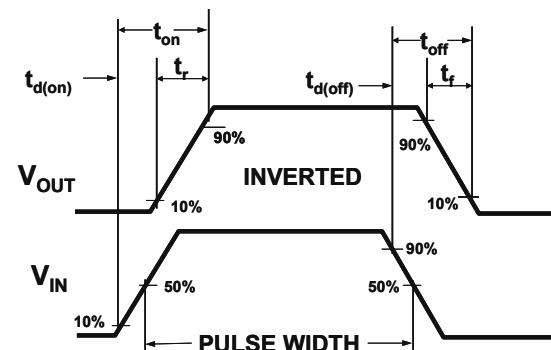


Figure 2:Switching Waveforms

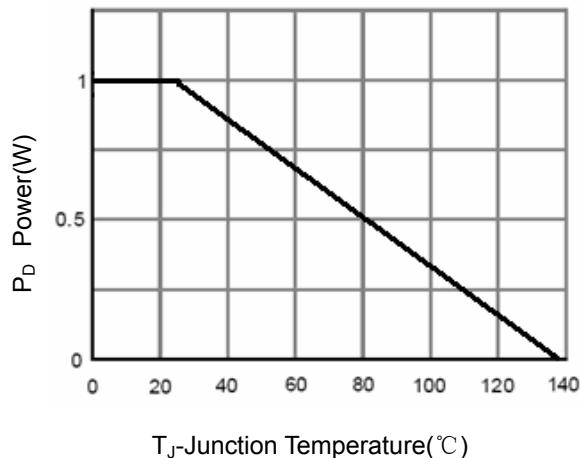


Figure 3 Power Dissipation

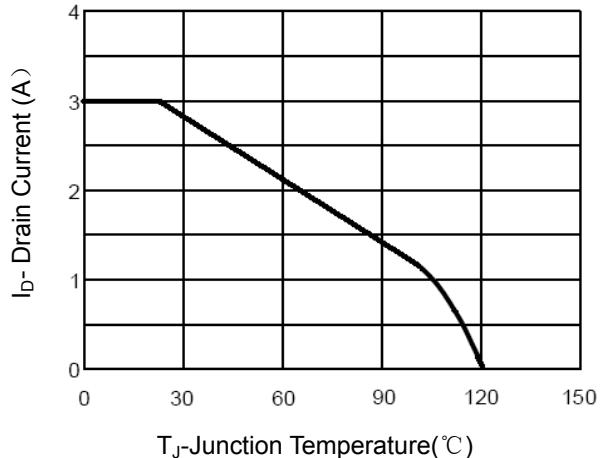


Figure 4 Drain Current

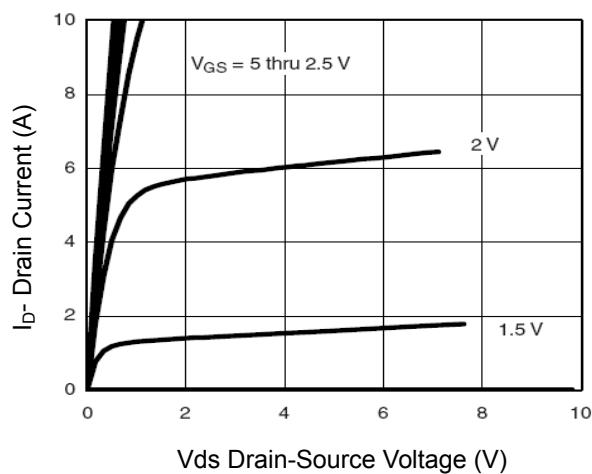


Figure 5 Output CHARACTERISTICS

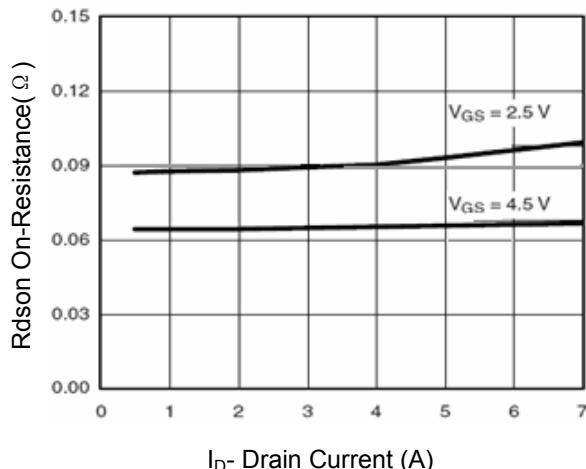
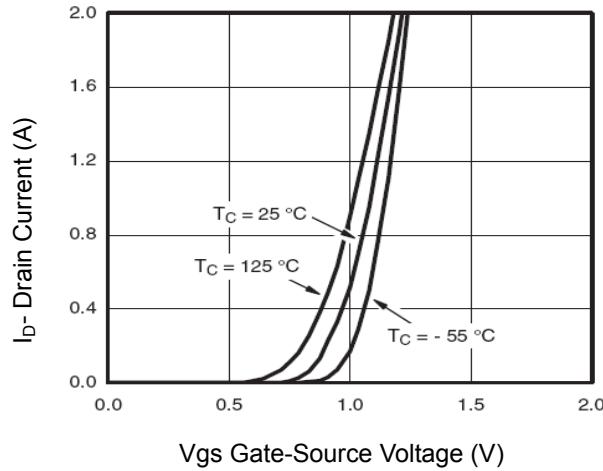
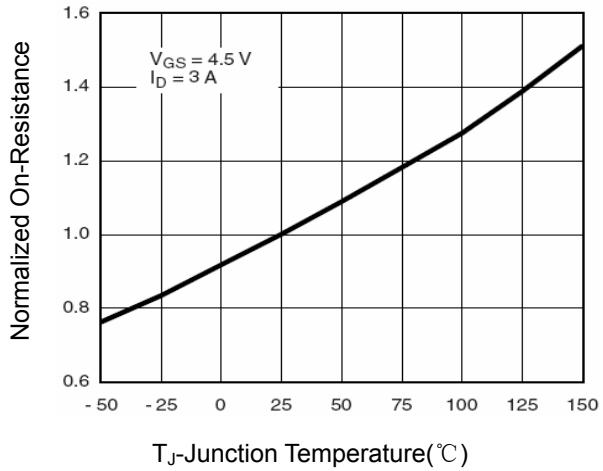
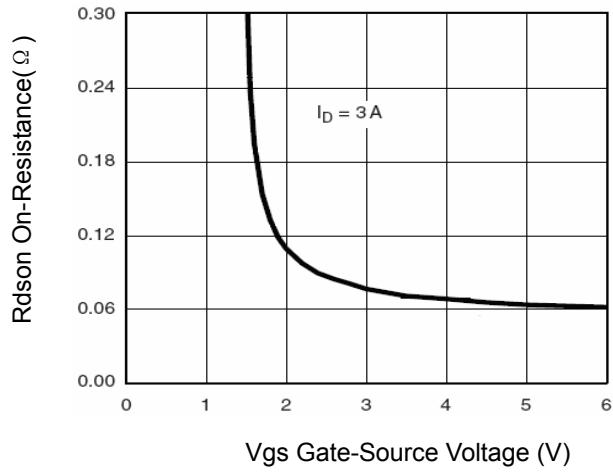
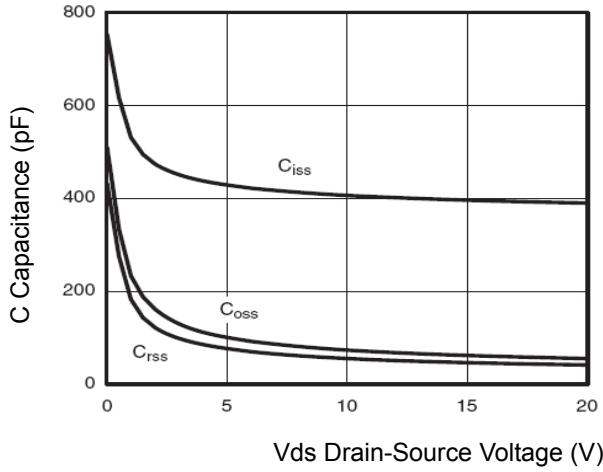
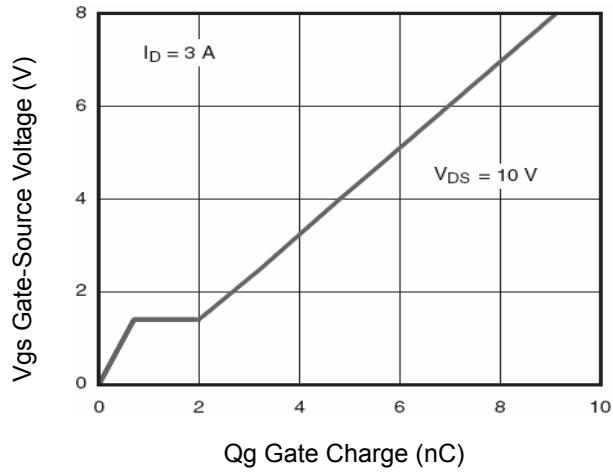
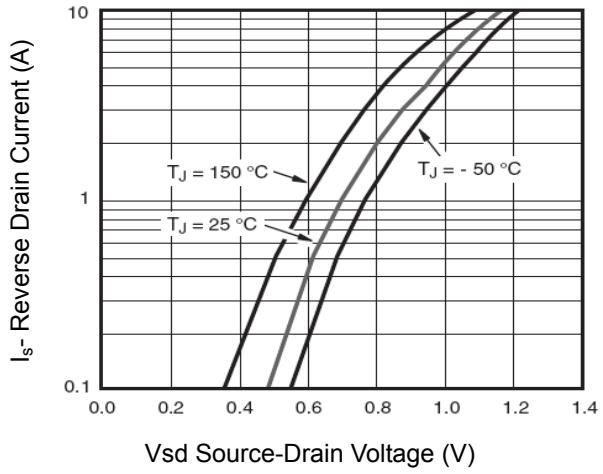


Figure 6 Drain-Source On-Resistance



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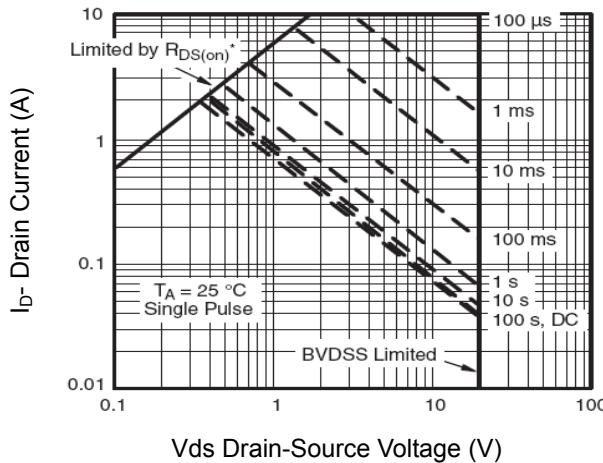
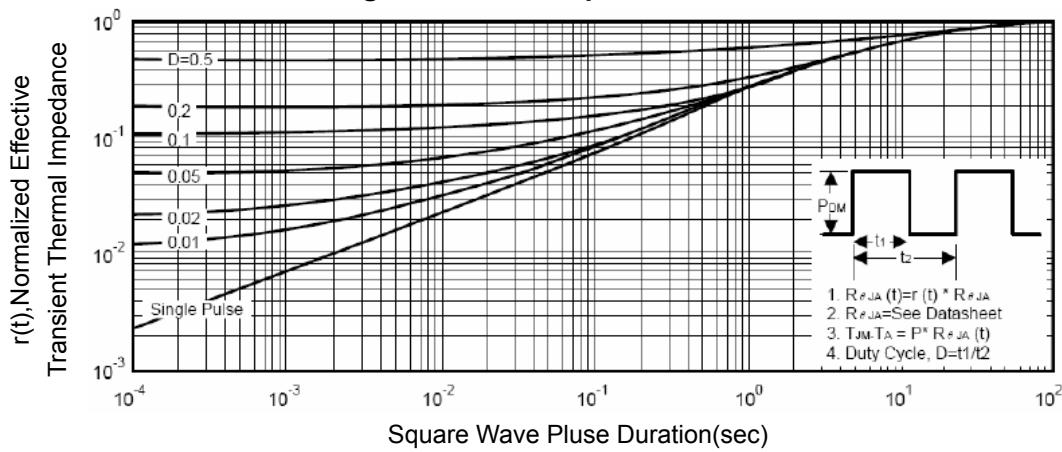
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**Figure 7 Transfer Characteristics****Figure 8 Drain-Source On-Resistance****Figure 9  $R_{DSON}$  vs  $V_{GS}$** **Figure 10 Capacitance vs  $V_{DS}$** **Figure 11 Gate Charge****Figure 12 Source- Drain Diode Forward**



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**Figure 13 Safe Operation Area****Figure 14 Normalized Maximum Transient Thermal Impedance**



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## PACKAGE OUTLINE

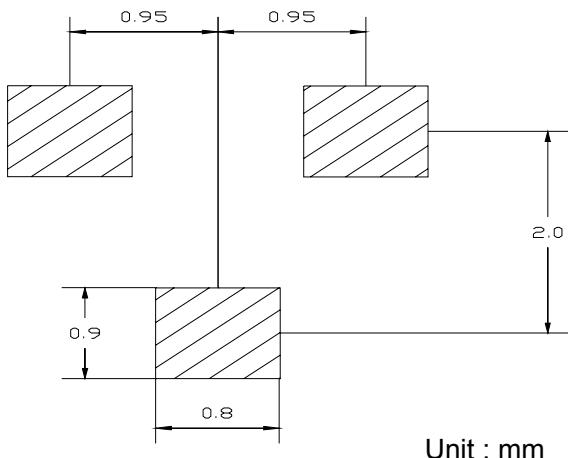
Plastic surface mounted package

SOT-23

SOT-23		
Dim	Min	Max
A	2.85	2.95
B	1.25	1.35
C	1.0Typical	
D	0.37	0.43
E	0.35	0.48
G	1.85	1.95
H	0.02	0.1
J	0.1Typical	
K	2.35	2.45

All Dimensions in mm

## SOLDERING FOOTPRINT



## PACKAGE INFORMATION

Device-marking	Device	Package	Shipping
A1SHB	SI2305DS	SOT-23	3000/Tape&Reel